

MSM41257AAS/RS

262,144-BIT DYNAMIC RANDOM ACCESS MEMORY <Nibble Mode Type>

GENERAL DESCRIPTION

The Oki MSM41257A is a fully decoded, dynamic NMOS random access memory organized as 262144 one-bit words. The design is optimized for high-speed, high performance applications such as mainframe memory, buffer memory, peripheral storage and environments where low power dissipation and compact layout is required.

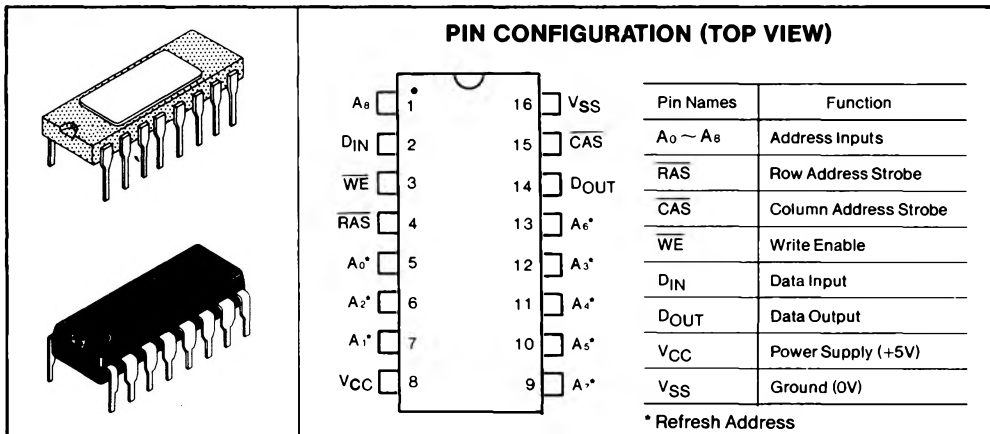
Multiplexed row and column address inputs permit the MSM41257A to be housed in a standard 16 pin DIP. Pin-outs conform to the JEDEC approved pin out. Additionally, the MSM41257A offers new functional enhancements that make it more versatile than previous dynamic RAMs. "CAS-before-RAS" refresh provides an on-chip refresh capability, also features "nibble mode" which allows high speed serial access to up to 4 bits of data.

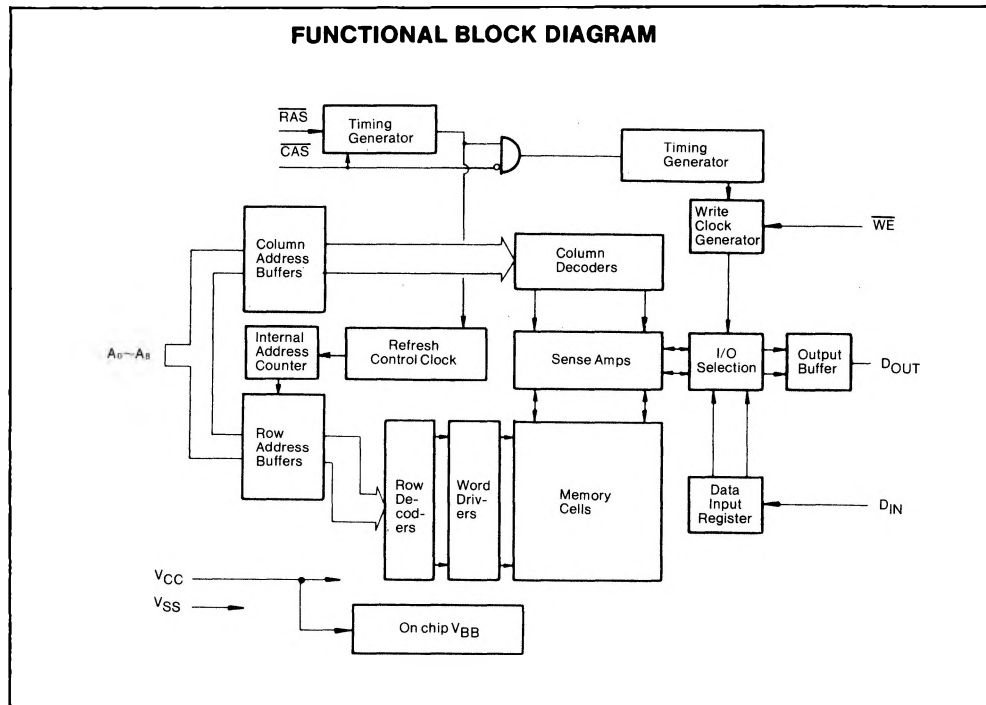
The MSM41257A is fabricated using silicon gate NMOS and Oki's advanced VLSI Polysilicon process. This process, coupled with single-transistor memory storage cells, permits maximum circuit density and minimum chip size. Dynamic circuitry is employed in the design, including the sense amplifiers.

Clock timing requirements are noncritical, and power supply tolerance is very wide. All inputs and output are TTL compatible.

FEATURES

- 262,144 × 1 RAM, 16 pin package
- Silicon-gate, Double Poly NMOS, single transistor cell
- Row access time:
 - 100 ns max (MSM41257A-10AS/RS)
 - 120 ns max (MSM41257A-12AS/RS)
 - 150 ns max (MSM41257A-15AS/RS)
- Cycle time:
 - 200 ns min (MSM41257A-10AS/RS)
 - 220 ns min (MSM41257A-12AS/RS)
 - 260 ns min (MSM41257A-15AS/RS)
- Low power:
 - 385 mW active, 28 mW max standby
- Single +5V Supply, ±10% tolerance
- All inputs TTL compatible, low capacitive load
- Three-state TTL compatible output
- "Gated" CAS
- 256 refresh cycles/4 ms
- Common I/O capability using "Early Write" operation
- Output unlatched at cycle end allows extended page boundary and two-dimensional chip select
- Read-Modify-Write, RAS-only refresh, capability
- On-chip latches for Addresses and Data-in
- On-chip substrate bias generator for high performance
- CAS-before-RAS refresh capability
- "Nibble Mode" capability





ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS (See Note)

Rating	Symbol	Value	Unit
Voltage on any pin relative to V _{SS}	V _{IN} , V _{OUT}	-1 to +7	V
Voltage on V _{CC} supply relative to V _{SS}	V _{CC}	-1 to +7	V
Operating temperature	T _{opr}	0 to 70	°C
Storage temperature	T _{stg}	-55 to +150	°C
Power dissipation	P _D	1.0	W
Short circuit output current		50	mA

Note: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

(Referenced to V_{SS})

Parameter	Symbol	Min.	Typ.	Max.	Unit	Operating Temperature
Supply Voltage	V_{CC}	4.5	5.0	5.5	V	0°C to +70°C
	V_{SS}	0	0	0	V	
Input High Voltage, all inputs	V_{IH}	2.4		6.5	V	
Input Low Voltage, all inputs	V_{IL}	-1.0		0.8	V	

DC CHARACTERISTICS

(Recommended operating conditions unless otherwise noted.)

Parameter	Symbol	Min.	Max.	Unit	Notes
OPERATING CURRENT* Average power supply current ($\overline{RAS}$, $\overline{CAS}$ cycling; $t_{RC} = \min.$)	I_{CC1}		70	mA	
STANDBY CURRENT Power supply current ($\overline{RAS} = \overline{CAS} = V_{IH}$)	I_{CC2}		5.0	mA	
REFRESH CURRENT 1 Average power supply current ($\overline{RAS}$ cycling, $\overline{CAS} = V_{IH}$; $t_{RC} = \min.$)	I_{CC3}		60	mA	
NIBBLE MODE CURRENT* Average power supply current ($\overline{RAS} = V_{IL}$, $\overline{CAS}$ cycling; $t_{NC} = \min.$)	I_{CC4}		30	mA	
REFRESH CURRENT 2 Average power supply current ($\overline{CAS}$ before $\overline{RAS}$; $t_{RC} = \min.$)	I_{CC5}		65	mA	
INPUT LEAKAGE CURRENT Input leakage current, any input ($0V \leq V_{IN} \leq 5.5V$, all other pins not under test = 0V)	I_{LI}	-10	10	μA	
OUTPUT LEAKAGE CURRENT (Data out is disabled, $0V \leq V_{OUT} \leq 5.5V$)	I_{LO}	-10	10	μA	
OUTPUT LEVELS Output high voltage ($I_{OH} = -5 \text{ mA}$) Output low voltage ($I_{OL} = 4.2 \text{ mA}$)	V_{OH} V_{OL}	2.4	0.4	V V	

Note*: I_{CC} is dependent on output loading and cycle rates. Specified values are obtained with the output open.

CAPACITANCE

(Ta = 25°C, f = 1 MHz)

Parameter	Symbol	Typ.	Max.	Unit
Input capacitance ($A_0 \sim A_8, D_{IN}$)	C_{IN1}	—	7	pF
Input capacitance ($RAS, \overline{CAS}, \overline{WE}$)	C_{IN2}	—	10	pF
Output capacitance (D_{OUT})	C_{OUT}	—	7	pF

Capacitance measured with Boonton Meter.

AC CHARACTERISTICS

(Recommended operating conditions unless otherwise noted.)

Note 1, 2, 3

Parameter	Symbol	Unit	MSM41257A-10		MSM41257A-12		MSM41257A-15		Notes
			Min.	Max.	Min.	Max.	Min.	Max.	
Refresh period	t _{REF}	ms		4		4		4	
Random read or write cycle time	t _{RC}	ns	200		220		260		
Read-write cycle time	t _{RWC}	ns	200		220		260		
Access time from $\overline{\text{RAS}}$	t _{RAC}	ns		100		120		150	4, 6
Access time from $\overline{\text{CAS}}$	t _{CAC}	ns		50		60		75	5, 6
Output buffer turn-off delay	t _{OFF}	ns	0	30	0	30	0	30	
Transition time	t _T	ns	3	50	3	50	3	50	
$\overline{\text{RAS}}$ precharge time	t _{RP}	ns	85		90		100		
$\overline{\text{RAS}}$ pulse width	t _{RAS}	ns	105	10μs	120	10μs	150	10μs	
$\overline{\text{RAS}}$ hold time	t _{RSH}	ns	55		60		75		
$\overline{\text{CAS}}$ pulse width	t _{CAS}	ns	55	10μs	60	10μs	75	10μs	
$\overline{\text{CAS}}$ hold time	t _{CSH}	ns	105		120		150		
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ delay time	t _{RCD}	ns	25	50	25	60	25	75	7
$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ set-up time	t _{CRS}	ns	20		20		20		
Row address set-up time	t _{ASR}	ns	0		0		0		
Row address hold time	t _{RAH}	ns	15		15		15		
Column address set-up time	t _{ASC}	ns	0		0		0		
Column address hold time	t _{CAH}	ns	20		20		25		
Read command set-up time	t _{RCS}	ns	0		0		0		
Read command hold time referenced to $\overline{\text{CAS}}$	t _{RCH}	ns	0		0		0		
Read command hold time referenced to $\overline{\text{RAS}}$	t _{RRH}	ns	20		20		20		
Write command set-up time	t _{WCS}	ns	0		0		0		8

AC CHARACTERISTICS (Continued)

(Recommended operating conditions unless otherwise noted.)

Parameter	Symbol	Unit	MSM41257A-10		MSM41257A-12		MSM41257A-15		Notes
			Min.	Max.	Min.	Max.	Min.	Max.	
Write command pulse width	tWP	ns	15		20		25		
Write command hold time	tWCH	ns	15		20		25		
Write command to RAS lead time	tRWL	ns	35		40		45		
Write command to CAS lead time	tCWL	ns	35		40		45		
Data-in set-up time	tDS	ns	0		0		0		
Data-in hold time	tDH	ns	20		20		25		
CAS to $\overline{WE}$ delay time	tCWD	ns	15		20		25		8
Refresh set-up time for CAS referenced to RAS	tFCS	ns	20		25		30		
Refresh hold time for CAS referenced to RAS	tFCH	ns	20		25		30		
CAS precharge time (C before R cycle)	tCPR	ns	20		25		30		
RAS precharge to CAS active time	tRPC	ns	20		20		20		
Nibble mode read/write cycle time	tNC	ns	55		60		70		9
Nibble mode read-write cycle time	tNRWC	ns	55		60		70		9
Nibble mode access time	tNCAC	ns		25		30		35	9
Nibble mode CAS pulse width	tNCAS	ns	25		30		35		9
Nibble mode CAS precharge time	tNCP	ns	20		25		30		9
Nibble mode read RAS hold time	tNRRSH	ns	25		30		40		9
Nibble mode write RAS hold time	tNWRSH	ns	45		50		60		9
Nibble mode CAS hold time referenced to RAS	tRNH	ns	20		20		20		9

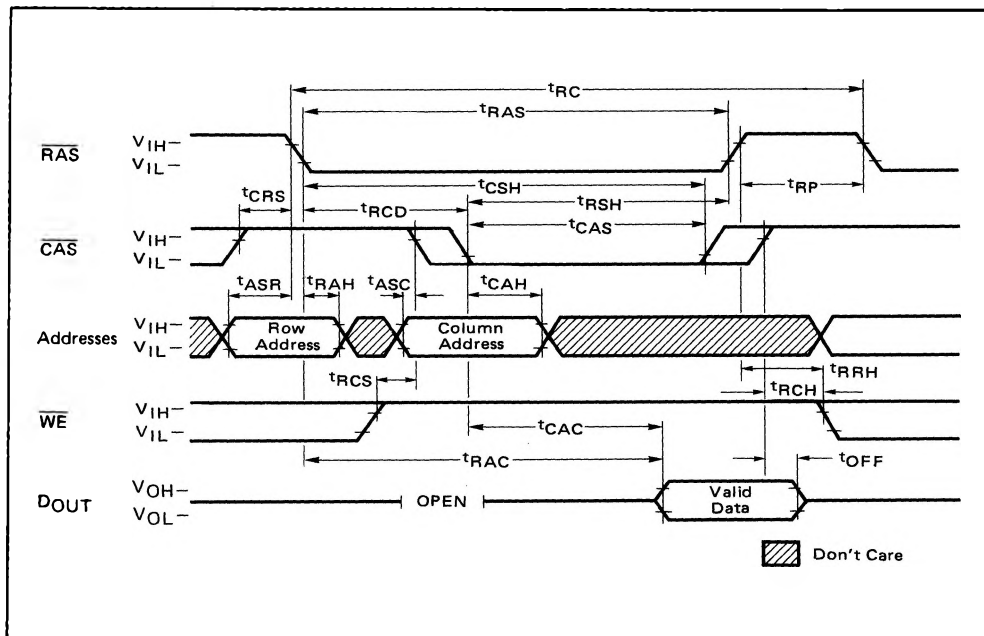
AC CHARACTERISTICS (Continued)

(Recommended operating conditions unless otherwise noted.)

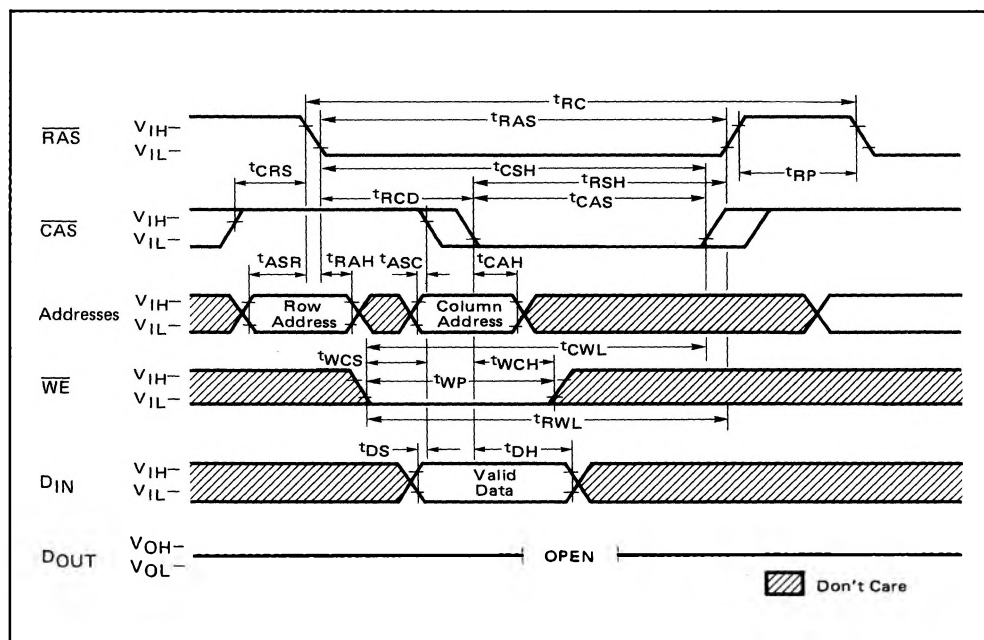
Parameter	Symbol	Unit	MSM41257A-10		MSM41257A-12		MSM41257A-15		Notes
			Min.	Max.	Min.	Max.	Min.	Max.	
Refresh counter test cycle time	t _{RTC}	ns	340		375		430		10
Refresh counter test RAS pulse width	t _{TRAS}	ns	230	10μs	265	10μs	320	10μs	10
Refresh counter test CAS precharge time	t _{CPT}	ns	50		60		70		10

- Notes:**
- 1 An initial pause of 100 μs is required after power-up followed by any 8 $\overline{\text{RAS}}$ cycles (Example: RAS only) before proper device operation is achieved.
 - 2 The AC characteristics assume at $t_T = 5$ ns
 - 3 V_{IH} (Min.) and V_{IL} (Max.) are reference levels for measuring of input signals. Also transition times are measured between V_{IH} and V_{IL} .
 - 4 Assumes that $t_{RCD} \leq t_{RCD} \text{ (Max.)}$. If t_{RCD} is greater than the maximum recommended value shown in this table, t_{RAC} will increase by the amount that t_{RCD} exceeds the value shown.
 - 5 Assumes that $t_{RCD} \geq t_{RCD} \text{ (Max.)}$.
 - 6 Measured with a load circuit equivalent to 2TTL loads and 100 pF.
 - 7 Operation within the $t_{RCD} \text{ (Max.)}$ limit insures that $t_{RAC} \text{ (Max.)}$ can be met. $t_{RCD} \text{ (Max.)}$ is specified as a reference point only; if t_{RCD} is greater than the specified $t_{RCD} \text{ (Max.)}$ limit, then access time is controlled exclusively by t_{CAC} .
 - 8 t_{WCS} and t_{CWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if $t_{WCS} \geq t_{WCS} \text{ (min.)}$, the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{CWD} \geq t_{CWD} \text{ (min.)}$, the cycle is read-write cycle and the data out will contain data read from the selected cell; if neither of the above sets of conditions is satisfied the condition of the data out (at access time) is indeterminate.
 - 9 Nibble mode cycle.
 - 10 $\overline{\text{CAS}}$ before RAS Refresh Counter Test Cycle only.

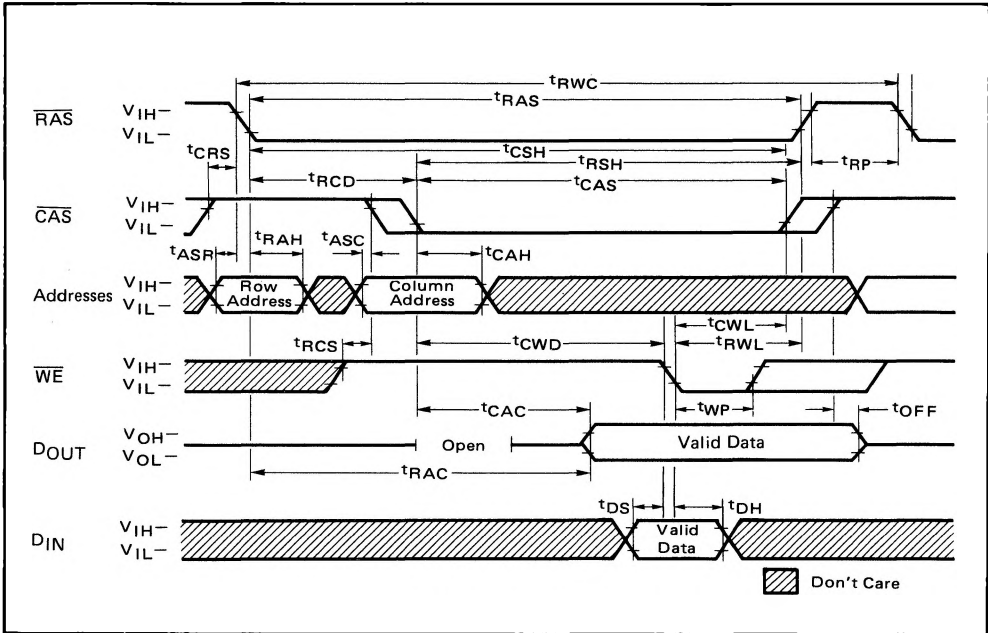
READ CYCLE



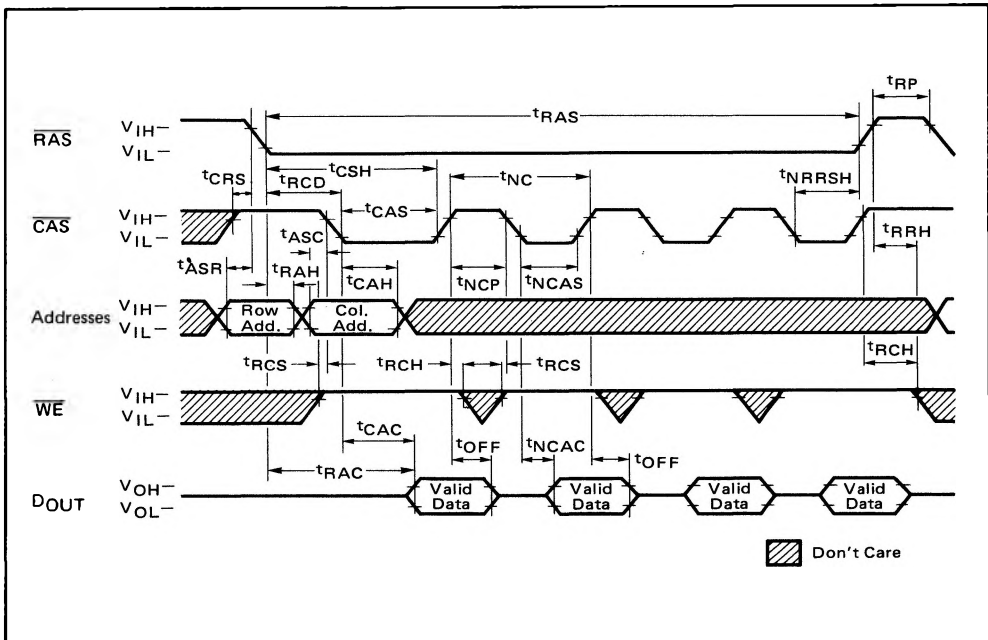
WRITE CYCLE (EARLY WRITE)



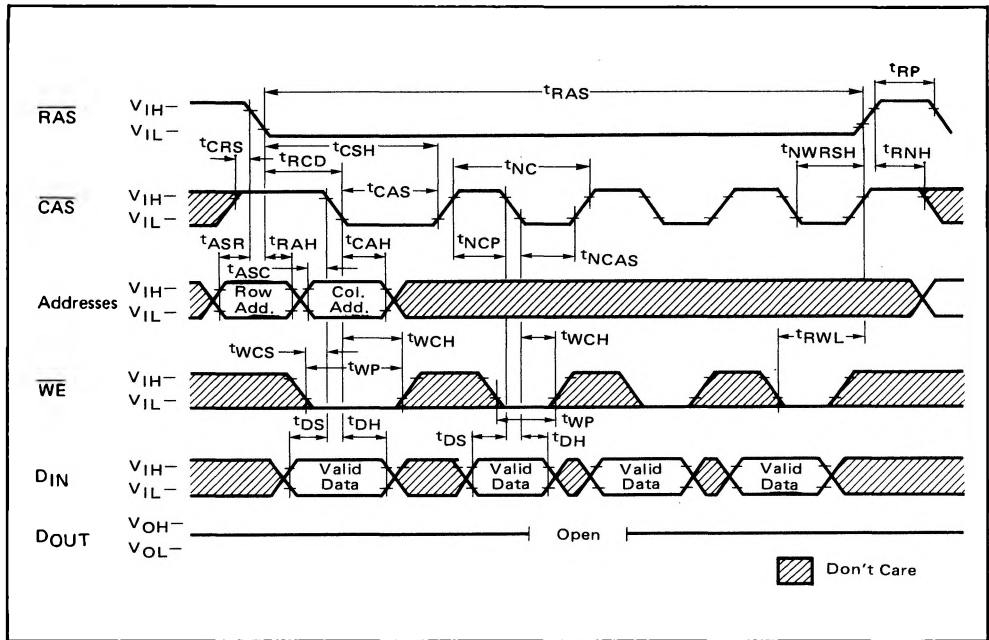
READ-WRITE/READ-MODIFY-WRITE CYCLE



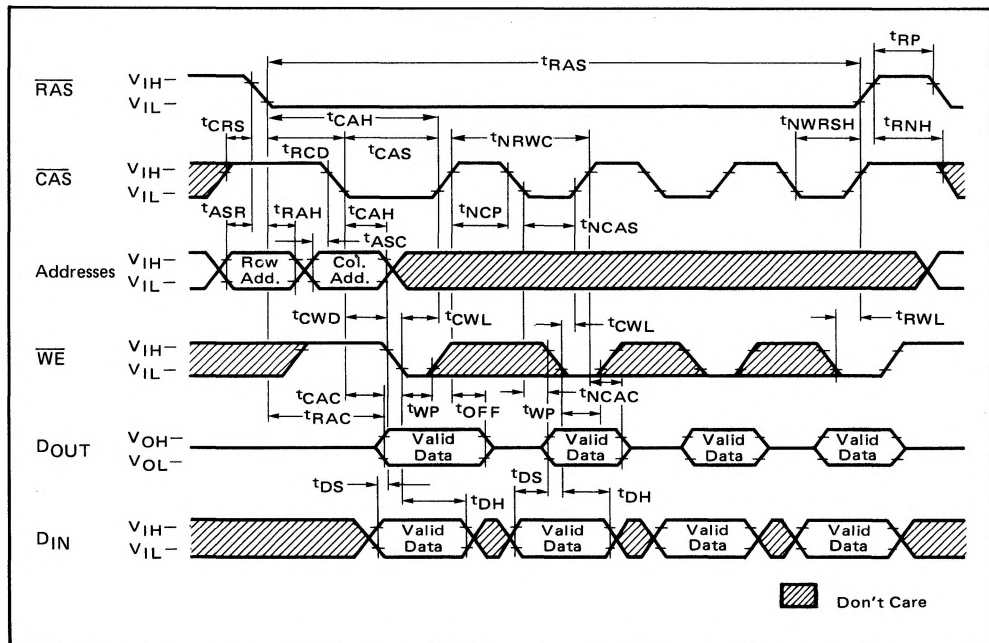
NIBBLE MODE READ CYCLE



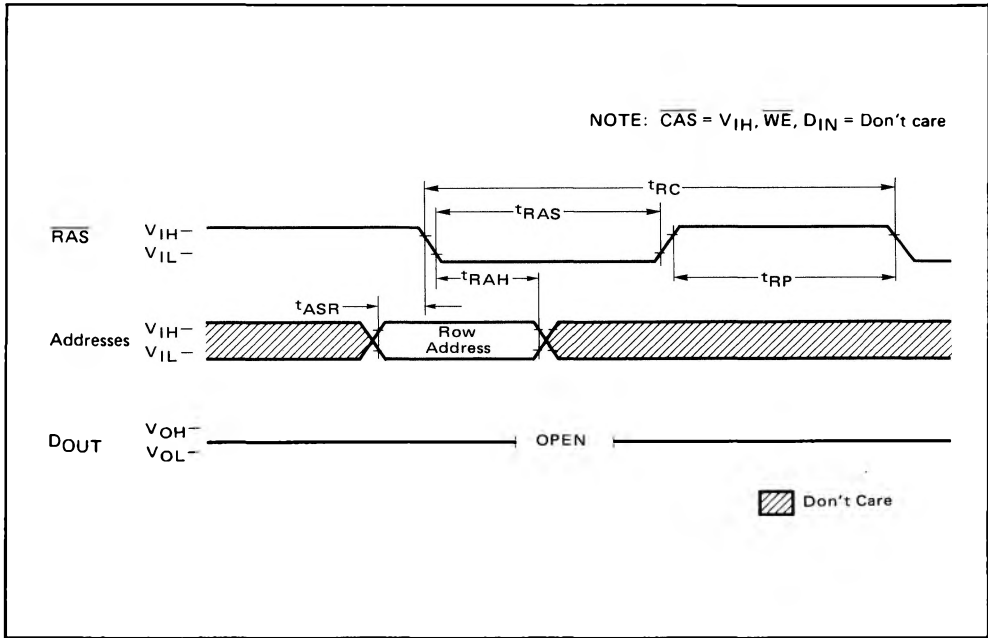
NIBBLE MODE WRITE CYCLE



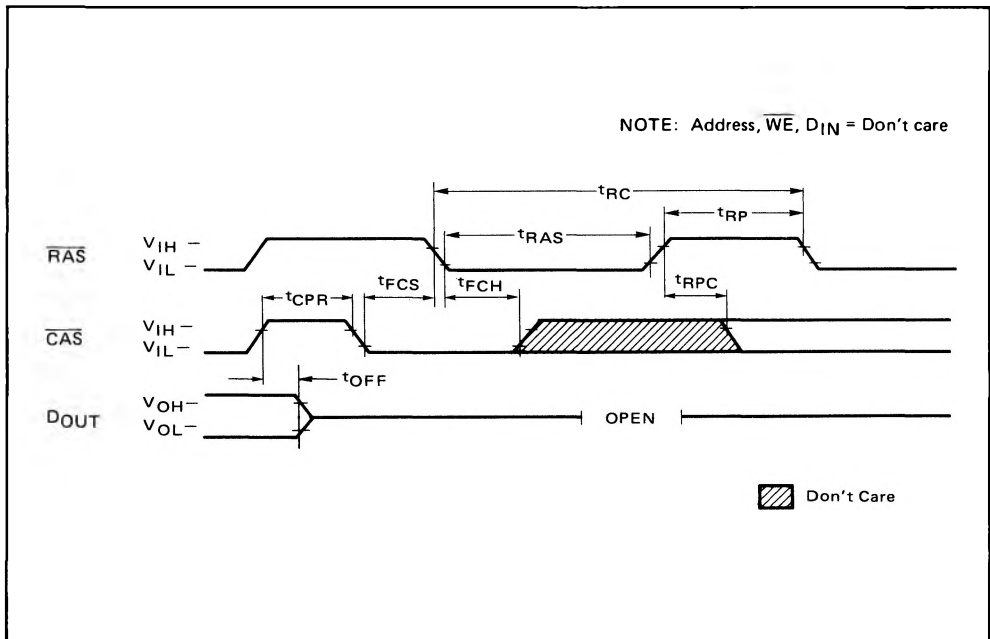
NIBBLE MODE READ-WRITE CYCLE



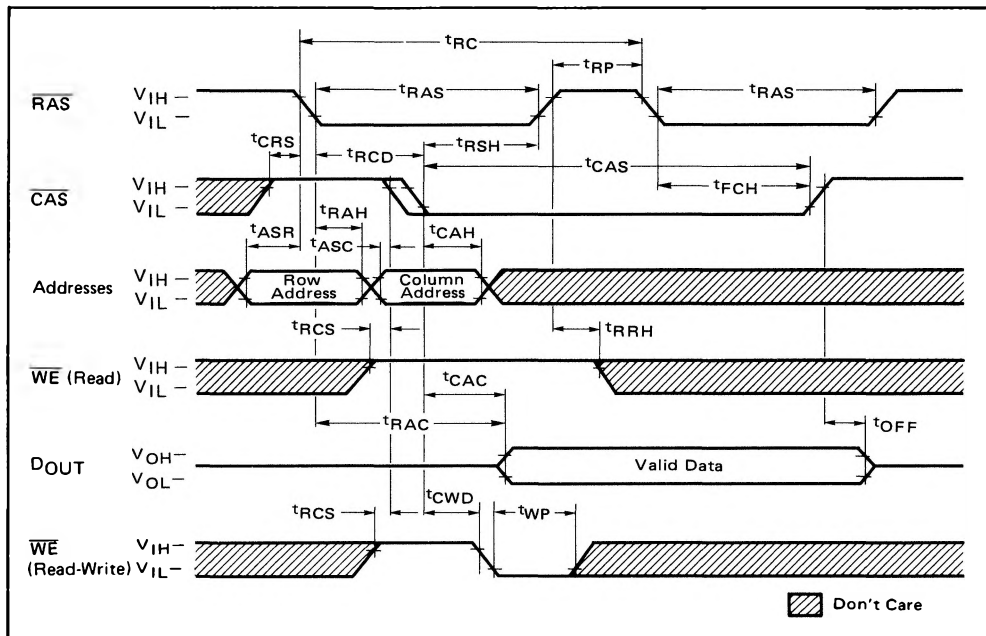
RAS ONLY REFRESH CYCLE



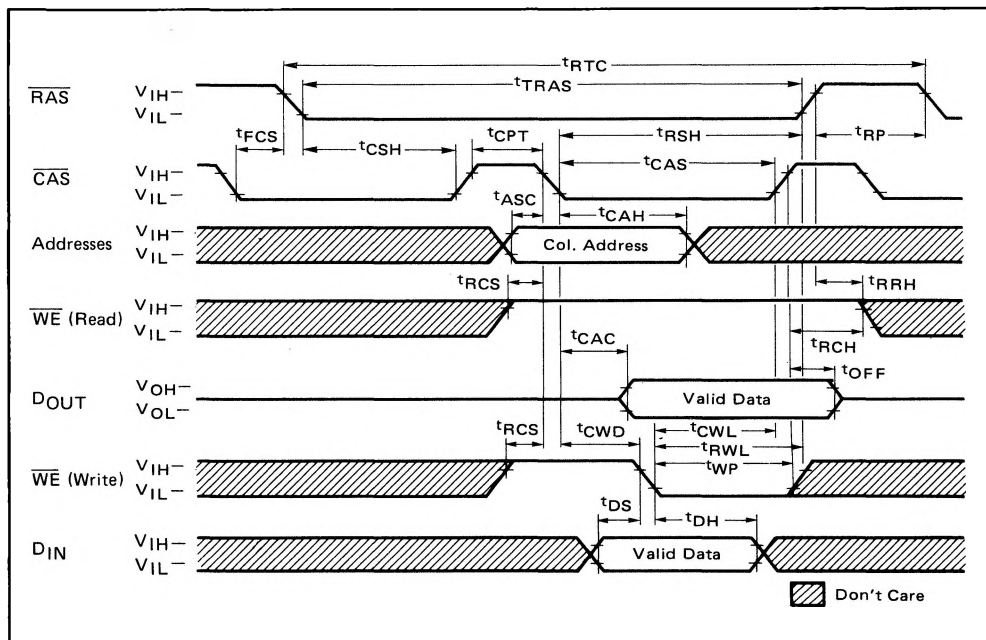
$\overline{\text{CAS}}$ -BEFORE- $\overline{\text{RAS}}$ REFRESH CYCLE



HIDDEN REFRESH CYCLE



CAS-BEFORE-RAS REFRESH COUNTER TEST CYCLE



FUNCTIONAL DESCRIPTION

Simple Timing Requirements:

The MSM41257A has the circuit considerations for easy operational timing requirements for high speed access time operations. The MSM41257A can operate under the condition of $t_{RCD}(\text{max}) = t_{CAC}$ which provides an optimal time space for address multiplexing. In addition, the MSM41257A has the minimal hold time of Address (t_{CAH}), $\overline{WE}$ (t_{WCH}) and D_{IN} (t_{DH}). And the MSM41257A can commit better memory system through-put during operations in an interleaved system. Furthermore, Oki has made timing requirements referenced to RAS non-restrictive and deleted from the data sheet, which includes t_{AR} , t_{WCR} , t_{DHR} and t_{RWD} . Therefore, the hold times of the Column Address D_{IN} and $\overline{WE}$ as well as t_{CWD} ($\overline{CAS}$ to $\overline{WE}$ Delay) are not restricted by t_{RCD} .

Fast Read- While-Write Cycle:

The MSM41257A has the fast read while write cycle which is achieved by excellent control of the three-state output buffer in addition to the simplified timings described in the previous section. The output buffer is controlled by the state of $\overline{WE}$ when $\overline{CAS}$ goes low. When $\overline{WE}$ is low during $\overline{CAS}$ transition to low, the MSM41257A goes to early write mode where the output becomes floating and common I/O bus can be used on the system level. Whereas, when $\overline{WE}$ goes low after t_{CWD} following $\overline{CAS}$ transition to low, the MSM41257A goes to delayed write mode where the output contains the data from the cell selected and the data from D_{IN} is written into the cell selected. Therefore, very fast read write cycle becomes available.

Address Inputs:

A total of eighteen binary input address bits are required to decode any 1 of 262,144 storage cell location within the MSM41257A. Nine row-address bits are established on the input pins (A_0 through A_8) and latched with the Row Address Strobe ($\overline{RAS}$). Then nine column address bits are established on the input pins and latched with the Column Address Strobe ($\overline{CAS}$). All input addresses must be stable on or before the falling edge of $\overline{RAS}$. $\overline{CAS}$ is internally inhibited (or "gated") by $\overline{RAS}$ to permit triggering of $\overline{CAS}$ as soon as the Row Address Hold Time (t_{RAH}) specification has been satisfied and the address inputs have been changed from row-addresses to column-addresses.

Write Enable:

The read or write mode is selected with the $\overline{WE}$ input. A logic "high" on $\overline{WE}$ dictates read mode, logic "low" dictates write mode. Data input is disabled when read mode is selected.

Data Input:

Data is written into the MSM41257A during a write or read-write cycle. The last falling edge of $\overline{WE}$ or $\overline{CAS}$ is a strobe for the Data in (D_{IN}) register. In a write cycle, if $\overline{WE}$ is brought "low" (write mode) before $\overline{CAS}$, D_{IN} is strobed by $\overline{CAS}$, and the set-up and hold times are referenced to $\overline{CAS}$. In a read-write cycle, $\overline{WE}$ will be delayed until $\overline{CAS}$ has made its negative transition. Thus D_{IN} is strobed by $\overline{WE}$, and set-up and hold times are referenced to $\overline{WE}$.

Data Output:

The output buffer is three-state TTL compatible with a fan-out of two standard TTL loads. Data out is the same polarity as data in. The output is in a high impedance state until $\overline{CAS}$ is brought "low". In a read cycle, or a read-write cycle, the output is valid after t_{RAC} from transition of RAS when $t_{RCD}(\text{max})$ is satisfied, or after t_{CAC} from transition of $\overline{CAS}$ when the transition occurs after $t_{RCD}(\text{max})$. Data remain valid until $\overline{CAS}$ is returned to "high". In a write cycle, the identical sequence occurs, but data is not valid.

Nibble Mode:

Nibble mode allows high speed serial read, write or read-modify-write access of 2, 3 or 4 bits of data. The bits of data that may be accessed during nibble mode are determined by the 8 row addresses and the 8 column addresses. The 2 bits of addresses ($\overline{CA}_8$, $\overline{RA}_8$) are used to select 1 of the 4 nibble bits for initial access. After the first bit is accessed by normal mode, the remaining nibble bits may be accessed by $\overline{CAS}$ "high" then "low" while RAS remains "low". Toggling $\overline{CAS}$ causes $\overline{RA}_8$ and $\overline{CA}_8$ to be incremented internally while all other address bits are held constant and makes the next nibble bit available for access. (See Table 1)

If more than 4 bits are accessed during nibble mode, the address sequence will begin to repeat. If any bit is written during nibble mode, the new data will be read on any subsequent access. If the write operation may be executed again on subsequent access, the new data will be written into the selected cell location.

In nibble mode, the three-state control of D_{OUT} Pin is determined by the first normal access cycle.

The data output is controlled by only $\overline{WE}$ state referenced at $\overline{CAS}$ negative transition of the normal cycle (first Nibble bit). That is, when $t_{WCS} > t_{WCS}(\text{min})$ is met, the data output will remain open circuit throughout the succeeding Nibble cycle regardless of $\overline{WE}$ state. Whereas, when $t_{CWD} > t_{CWD}(\text{min})$ is met, the data output will contain data from the cell selected during the succeeding nibble cycle regardless of $\overline{WE}$ state. The write operation is done during the period where $\overline{WE}$ and $\overline{CAS}$ clocks are low. Therefore, write operation can be done bit by bit during each nibble operation at any timing conditions of $\overline{WE}$ (t_{WCS} and t_{CWD}) at the normal cycle (first Nibble bit).

Table 1 NIBBLE MODE ADDRESS SEQUENCE EXAMPLE

SEQUENCE	NIBBLE BIT	RA ₈	ROW ADDRESS	CA ₈	COLUMN ADDRESS	
RAS/CAS (normal mode)	1	0	10101010	0	10101010	... input addresses
toggle $\overline{\text{CAS}}$ (nibble mode)	2	1	10101010	0	10101010	} generated inter- nally sequence repeats
toggle $\overline{\text{CAS}}$ (nibble mode)	3	0	10101010	1	10101010	
toggle $\overline{\text{CAS}}$ (nibble mode)	4	1	10101010	1	10101010	
toggle $\overline{\text{CAS}}$ (nibble mode)	1	0	10101010	0	10101010	

RAS Only Refresh:

Refresh of the dynamic memory cells is accomplished by performing a memory cycle at each of the 256 row-addresses (A₀ to A₇) at least every 4 milliseconds. RAS only refresh avoids any output during refresh because the output buffer is in the high impedance state unless CAS is brought low. Strobing each of the 256 row-addresses (A₀ to A₇) with RAS will cause all bits in each row to be refreshed. Further RAS only refresh results in a substantial reduction in power dissipation.

CAS Before RAS Refresh:

CAS before RAS refreshing available on the MSM41257A offers an alternate refresh method. If $\overline{\text{CAS}}$ is held on low for the specified period (t_{FCS}) before RAS goes to low, on chip refresh control clock generators and the refresh address counter are enabled, and an internal refresh operation takes place. After the refresh operation is performed, the refresh address counter is automatically incremented in preparation for the next CAS before RAS refresh operation.

Hidden Refresh:

Hidden refresh cycle may take place while maintaining latest valid data at the output by extending $\overline{\text{CAS}}$ active time from the previous memory read cycle. In MSM41257A hidden refresh means CAS before RAS refresh and the internal refresh addresses from the counter are used to refresh addresses, because $\overline{\text{CAS}}$ is always low when RAS goes to low in this mode.

CAS Before RAS Refresh Counter Test Cycle:

A special timing sequence using CAS before RAS counter test cycle provides a convenient method of verifying the functionality of $\overline{\text{CAS}}$ before RAS refresh activated circuitry. As shown in CAS before RAS Counter Test Cycle, if $\overline{\text{CAS}}$ goes to high and goes to low again while RAS is held low, the read and write operation are enabled. A memory cell address, consisting of a row address (9 bits) and a column address (9 bits), to be accessed can be defined as follows:

*** A ROW ADDRESS**

- Bits A₀ through A₇ are defined by the refresh counter. The other bit A₈ is set "high" internally.

*** A COLUMN ADDRESS**

- All the bits A₀ through A₈ are defined by latching levels on A₀ through A₈ at the second falling edge of CAS.

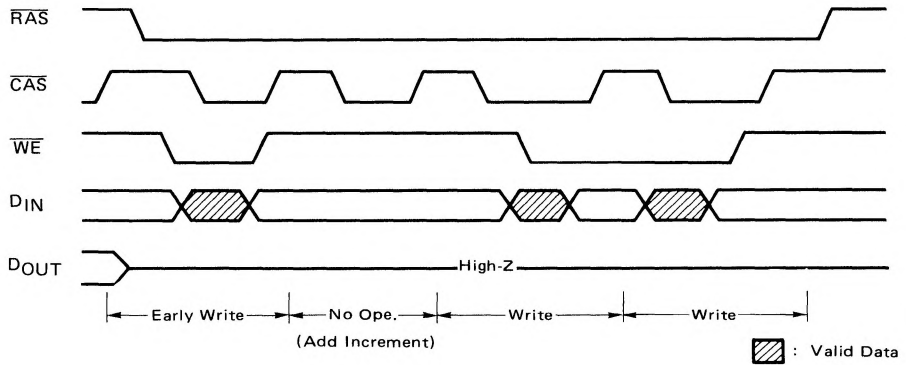
Suggested CAS before RAS Counter Test Procedure:

The timing, as shown in $\overline{\text{CAS}}$ before RAS Counter Test Cycle, is used for all the operations described as follows:

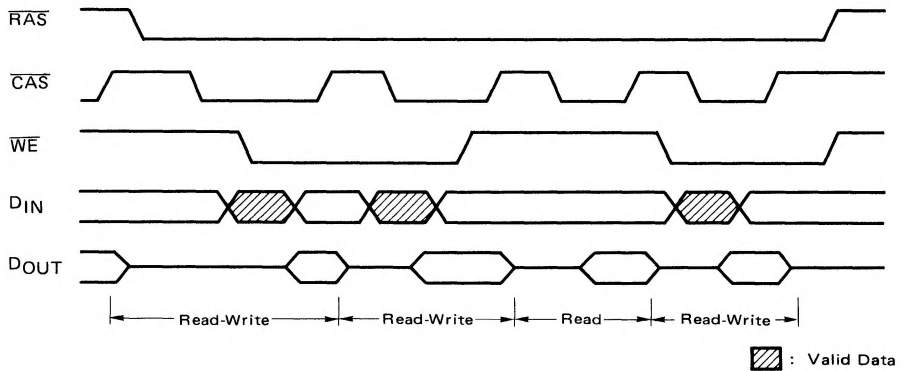
- (1) Initialize the internal refresh counter. For this operation, 8 cycles are required.
- (2) Write a test pattern of lows into memory cells at a single column address and 256 row addresses.
- (3) By using read-modify-write cycle, read the low written at the last operation (Step (2)) and write a new high in the same cycle. This cycle is repeated 256 times, and highs are written into the 256 memory cells.
- (4) Read the high written at the last operation (Step (3)).
- (5) Complement the test pattern and repeat the steps (2), (3) and (4).

NIBBLE MODE

1) The case of first nibble cycle is Early write



2) The case of first nibble cycle is delayed write (Read-Write)



MSM41257A Bit Map (Physical-Decimal)

□ Pin 16

252	253	254	255	COLUMN DECODER	3	2	1	0	256	257	258	259	COLUMN DECODER	511	510	509	508
0	0	0	0		0	0	0	0	0	0	0	0		0	0	0	0
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
256	256	256	256		256	256	256	256	256	256	256	256		256	256	256	256
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
1	1	1	1		1	1	1	1	1	1	1	1		1	1	1	1
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
257	257	257	257		257	257	257	257	257	257	257	257		257	257	257	257
252	253	254	255	COLUMN DECODER	3	2	1	0	256	257	258	259	COLUMN DECODER	511	510	509	508
126	126	126	126		126	126	126	126	126	126	126	126		126	126	126	126
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
382	382	382	382		382	382	382	382	382	382	382	382		382	382	382	382
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
127	127	127	127		127	127	127	127	127	127	127	127		127	127	127	127
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
383	383	383	383		383	383	383	383	383	383	383	383		383	383	383	383

ROW DECODER

ROW DECODER

252	253	254	255	COLUMN DECODER	3	2	1	0	256	257	258	259	COLUMN DECODER	511	510	509	508
511	511	511	511		511	511	511	511	511	511	511	511		511	511	511	511
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
255	255	255	255		255	255	255	255	255	255	255	255		255	255	255	255
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
510	510	510	510		510	510	510	510	510	510	510	510		510	510	510	510
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
254	254	254	254		254	254	254	254	254	254	254	254		254	254	254	254
252	253	254	255	COLUMN DECODER	3	2	1	0	256	257	258	259	COLUMN DECODER	511	510	509	508
385	385	385	385		385	385	385	385	385	385	385	385		385	385	385	385
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
129	129	129	129		129	129	129	129	129	129	129	129		129	129	129	129
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
384	384	384	384		384	384	384	384	384	384	384	384		384	384	384	384
252	253	254	255		3	2	1	0	256	257	258	259		511	510	509	508
128	128	128	128		128	128	128	128	128	128	128	128		128	128	128	128

A8 ROW = "L"
REFRESH ADDRESS

A8 ROW = "H"
REFRESH ADDRESS

(0 - 255)

(0 - 255)

□
Pin 8
A
B
: CELL

A = ROW ADDRESS (DECIMAL)
B = COLUMN ADDRESS (DECIMAL)